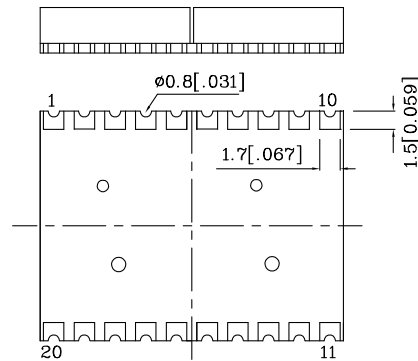
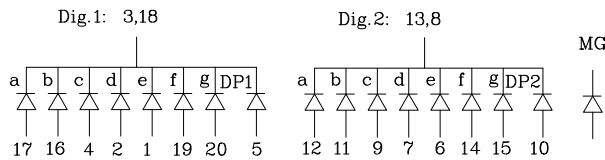
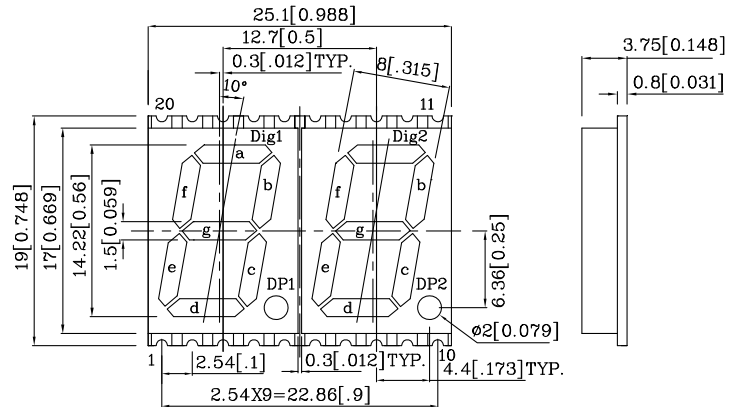


Features

- 0.56 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE : 200PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



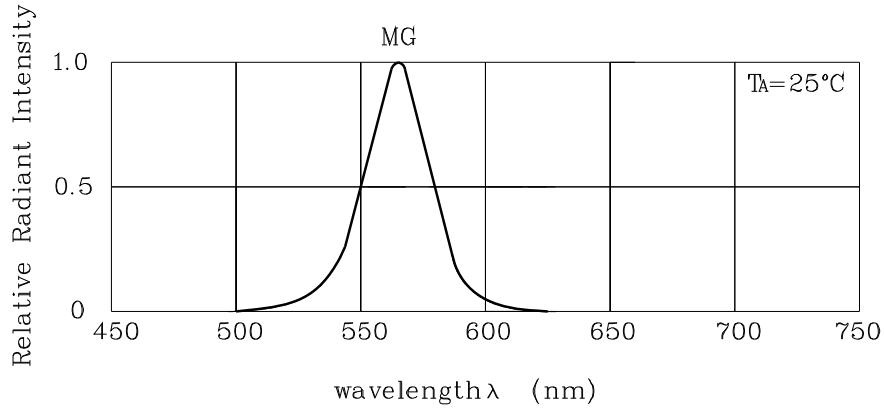
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (TA=25°C)		MG (GaP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation	PT	62.5	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

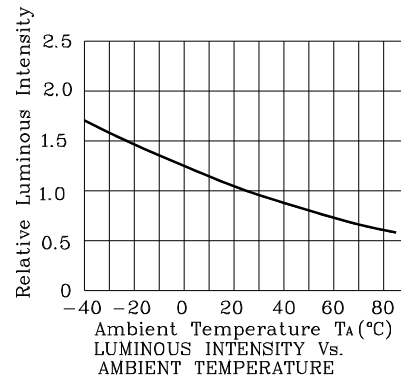
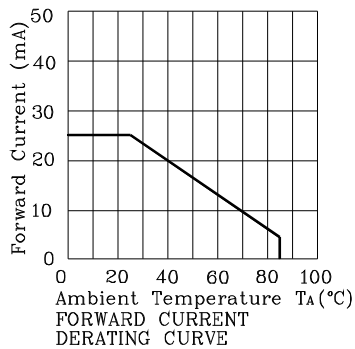
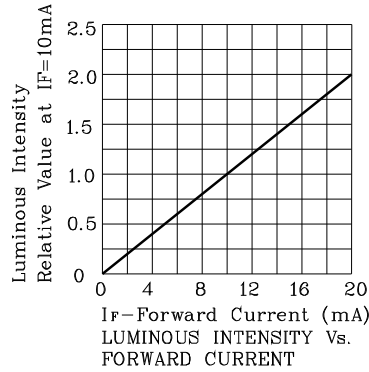
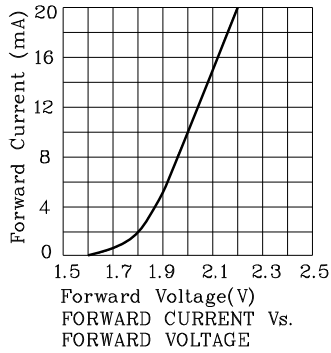
Operating Characteristics (TA=25°C)	MG (GaP)	Unit
Forward Voltage (Typ.) (IF=10mA)	VF	2.0 V
Forward Voltage (Max.) (IF=10mA)	VF	2.5 V
Reverse Current (Max.) (VR=5V)	IR	10 uA
Wavelength of Peak Emission (Typ.) (IF=10mA)	λP	565 nm
Wavelength of Dominant Emission (Typ.) (IF=10mA)	λD	568 nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=10mA)	$\Delta\lambda$	30 nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	15 pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA)		Wavelength nm λP	Description
			min.	typ.		
ZFMG14C2	Green	GaP	3000	13190	565	Common Cathode. Rt. Hand Decimal



RELATIVE INTENSITY Vs. WAVELENGTH

❖ MG



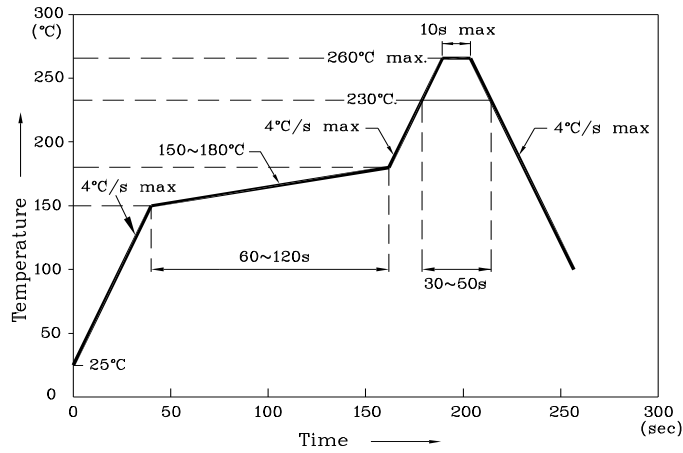
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

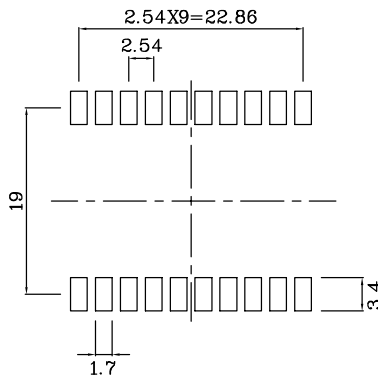
Reflow Soldering Profile For Lead-free SMT Process.



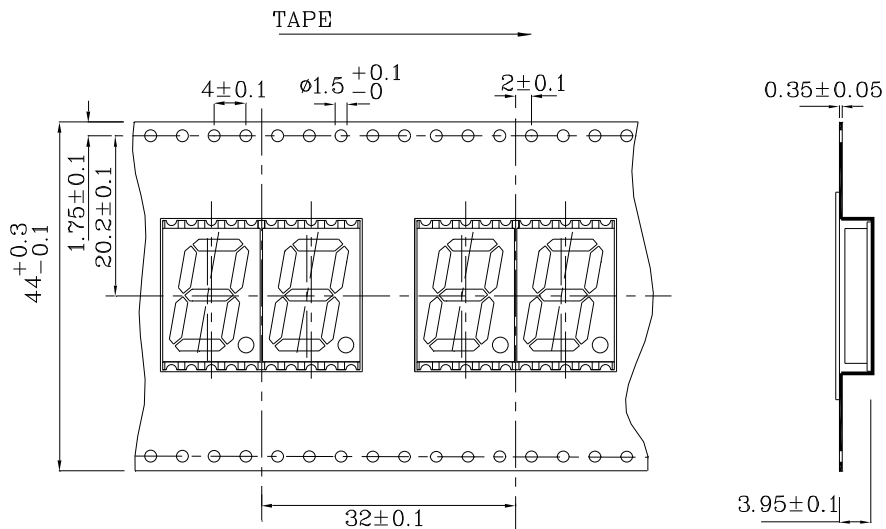
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:± 0.15)



❖ Tape Specification (Units : mm)



PACKING & LABEL SPECIFICATIONS

ZFMG14C2

